

# **DUAL N-CHANNEL MOSFET**

## DESCRIPTION

NEC

The  $\mu$ PA2352B is a Dual N-channel MOSFET designed for Lithium-Ion battery protection circuit.

Ecologically Flip chip MOSFET for Lithium-Ion battery Protection (EFLIP).

## **FEATURES**

- Monolithic Dual MOSFET
  Connecting the Drains on the circuit board is not required because the Drains of the FET1 and the FET2 are internally
- connected. • 2.5 V drive available and low on-state resistance Rss(on)1 = 43.0 m $\Omega$  MAX. (Vgs = 4.5 V, Is = 2.0 A) Rss(on)2 = 45.0 m $\Omega$  MAX. (Vgs = 4.0 V, Is = 2.0 A) Rss(on)3 = 55.0 m $\Omega$  MAX. (Vgs = 3.1 V, Is = 2.0 A) Rss(on)4 = 67.0 m $\Omega$  MAX. (Vgs = 2.5 V, Is = 2.0 A)
- Built-in G-S protection diode against ESD
- Pb-free Bump

### ORDERING INFORMATION

PART NUMBER	PACKAGE
μΡΑ2352ΒΤ1G-Ε4-Α <sup>Νote</sup>	4-pin EFLIP

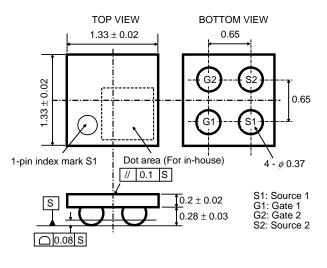
Note Pb-free (This product does not contain Pb in the external electrode and other parts.)

**Remark** "-E4" indicates the unit orientation (E4 only).

### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^{\circ}C$ )

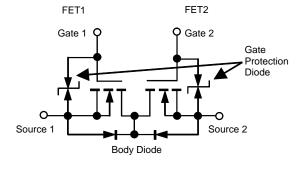
Vsss	24	V
Vgss	±12	V
IS(DC)	±4.0	Α
S(pulse)	±33	Α
Pτ	0.75	W
Tch	150	°C
Tstg	-55 to +150	°C
	VGSS Is(DC) Is(pulse) PT Tch	VGSS      ±12        Is(DC)      ±4.0        Is(pulse)      ±33        PT      0.75        Tch      150

**Notes 1.** Mounted on BT resin board of 40.5 mm x 25 mm x 1.5 mmt **2.** PW  $\leq$  100  $\mu$ s, Duty Cycle  $\leq$  1%



**OUTLINE DRAWING (Unit: mm)** 





**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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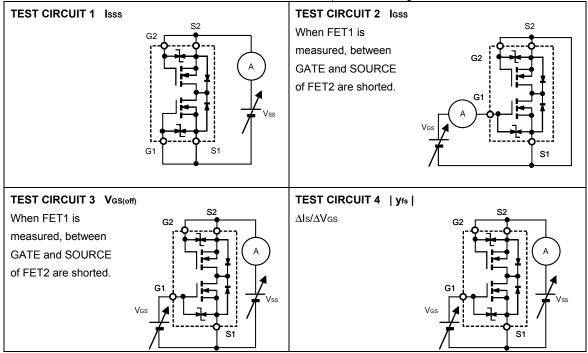
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CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
			ivin 4.			-
Zero Gate Voltage Source Current	Isss	Vss = 24 V, Vcs = 0 V, TEST CIRCUIT 1			10	μA
Gate Leakage Current	Igss	$V_{GS}$ = ±12 V, $V_{SS}$ = 0 V, TEST CIRCUIT 2			±10	μA
Gate to Source Cut-off Voltage	VGS(off)	Vss = 10.0 V, Is = 1.0 mA, TEST CIRCUIT 3	0.5	1.0	1.5	V
Forward Transfer Admittance Note	yfs	Vss = 10.0 V, Is = 2.0 A, TEST CIRCUIT 4	1.8			S
Source to Source On-state	RSS(on)1	V <sub>GS</sub> = 4.5 V, Is = 2.0 A, TEST CIRCUIT 5	24.0	35.0	43.0	mΩ
Resistance Note	RSS(on)2	V <sub>GS</sub> = 4.0 V, Is = 2.0 A, TEST CIRCUIT 5	25.0	37.0	45.0	mΩ
	RSS(on)3	V <sub>GS</sub> = 3.1 V, Is = 2.0 A, TEST CIRCUIT 5	31.5	43.0	55.0	mΩ
	Rss(on)4	V <sub>GS</sub> = 2.5 V, Is = 2.0 A, TEST CIRCUIT 5	33.5	55.0	67.0	mΩ
Input Capacitance	Ciss	Vss = 10.0 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz		720		pF
Output Capacitance	Coss	TEST CIRCUIT 7		130		pF
Reverse Transfer Capacitance	Crss			80		pF
Turn-on Delay Time	td(on)	V <sub>DD</sub> = 20.0 V, Is = 4.0 A,		2.5		μs
Rise Time	tr	$V_{GS}$ = 4.0 V, $R_{G}$ = 6.0 $\Omega$ ,		5.3		μs
Turn-off Delay Time	td(off)	TEST CIRCUIT 8		5.6		μs
Fall Time	tr			7.1		μs
Total Gate Charge	QG	V <sub>DD</sub> = 16 V, V <sub>G1S1</sub> = 4.0 V, I <sub>S</sub> = 4.0 A, TEST CIRCUIT 9		5.0		nC
Body Diode Forward Voltage Note	V <sub>F(S-S)</sub>	IF = 4.0 A, VGS = 0 V, TEST CIRCUIT 6		1.0		V

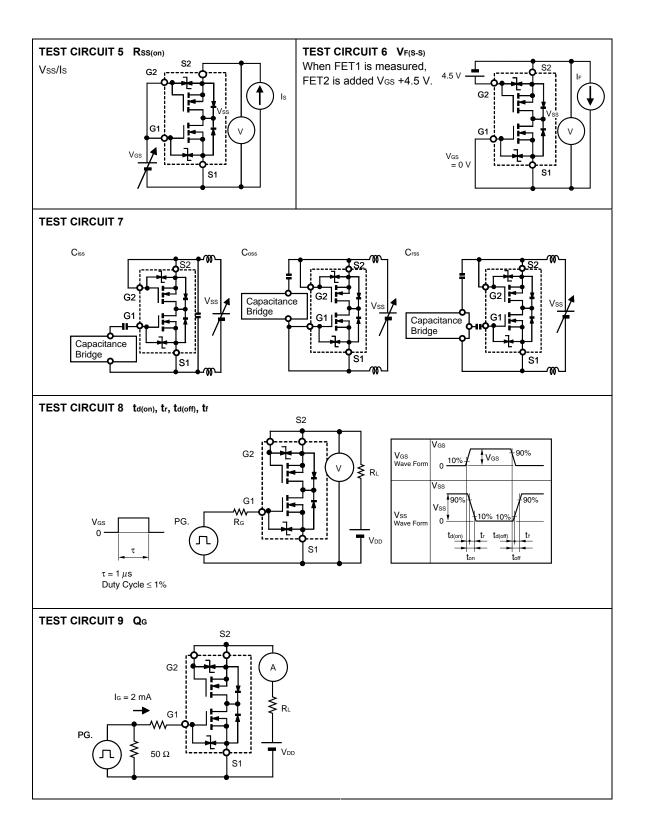
## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ ) These are common to FET1 and FET2.

Note Pulsed

## Both the FET1 and the FET2 are measured. Test circuits are example of measuring the FET1 side.

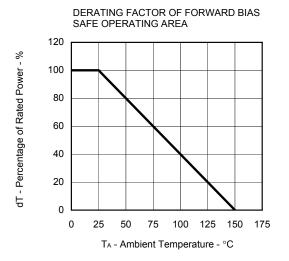


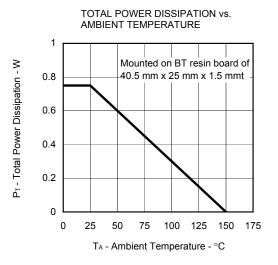
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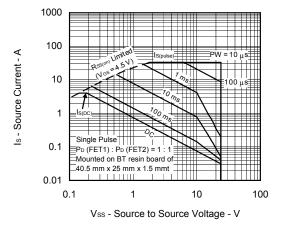
Data Sheet G19314EJ1V0DS

## TYPICAL CHARACTERISTICS (TA = 25°C)

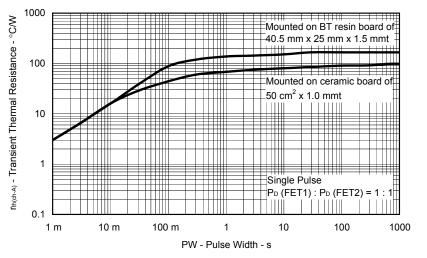








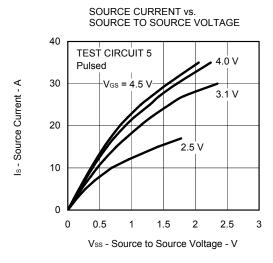
### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



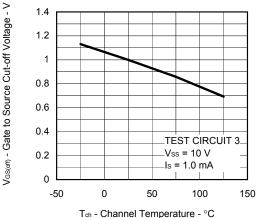
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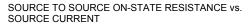
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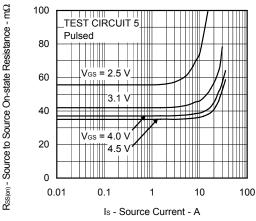




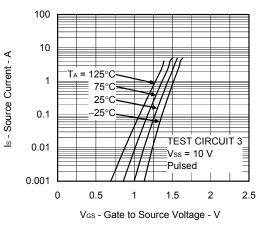




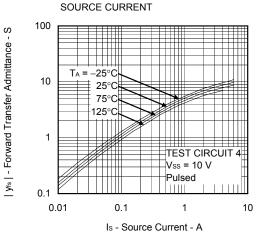




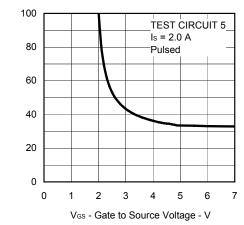




FORWARD TRANSFER ADMITTANCE vs.



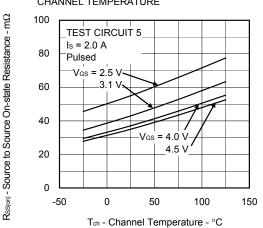
SOURCE TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



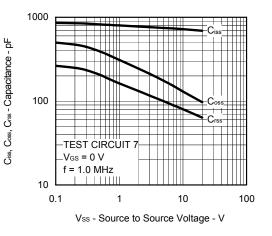
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Rss(on) - Source to Source On-state Resistance - mΩ

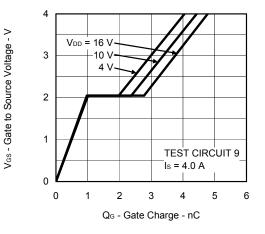
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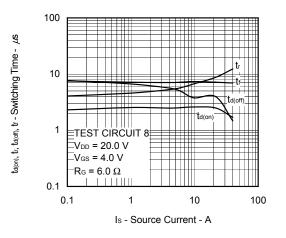
SOURCE TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE CAPACITANCE vs. SOURCE TO SOURCE VOLTAGE



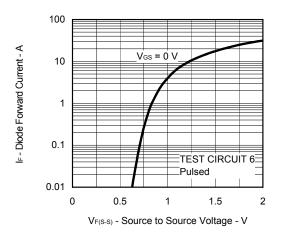
DYNAMIC INPUT CHARACTERISTICS



#### SWITCHING CHARACTERISTICS



SOURCE TO SOURCE DIODE FORWARD VOLTAGE



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